

## Full Wafer & Singulated Die / Module Test System with Automatic Wafer Handling System

High Volume Test and Reliability Verification Solution for Power, Photonics, Logic & Memory Devices



### System Benefits

- **High Throughput Reliability Verification and Test System for Volume Production**
  - ◆ Handles full wafers / panels / singulated die / modules for highest production throughput
  - ◆ Identifies failing logic / memory / photonic die before final package integration
  - ◆ Up to 18 Blades (slots) for wafer or panel testing using WaferPak<sup>TM</sup> contactors or 9 Blade capability for wafers / singulated die / module DiePak<sup>®</sup> carriers
  - ◆ Advanced high-power testing capability with up to 3,500 watts of power per wafer
- **Configurable Channel Resources**
  - ◆ Up to 4 modules available per Blade in 18 blade, or 8 modules in 9 blade configuration:
  - ◆ Universal Channel Modules (UCCM) with up to 2,048 resources (I/O / Clock / PPMU / DPS) per Blade with deep scan, pattern data and capture memory for testing of devices with BIST/DFT capabilities

*“Setting the Test Standard for Tomorrow”*

#### CORPORATE HEADQUARTERS

400 Kato Terrace  
Fremont, CA 94539  
Phone: (510) 623-9400  
Fax: (510) 623-9450  
Visit us at: [www.aehr.com](http://www.aehr.com)



- ◆ High Voltage Power Channel Modules (HVPCM) with up to 1,024 29V channels
- ◆ High Current Channel Modules (HCCM) with up to 1,024 2A channels
- ◆ BiPolar Voltage Channel Modules (BVCM) with up to 1,024 channels from -30V to 40V
- ◆ Very High Voltage Channel Modules (VHVCM) single channel up to 2,000V
  
- **Production Proven Full-Wafer Reliability Verification & Test Solution**
  - ◆ Reduces test costs by functionally testing wafers/die/modules during reliability verification
  - ◆ Offers a total solution when configured with a WaferPak contactor / DiePak carrier and Wafer Aligner / DiePak Loader
  - ◆ Protects devices with individual per channel over-current and over-voltage protection
  
- **Integrated Automated Wafer Handling and Alignment System**
  - ◆ Fully automated material handling in a hands-free operation.
  - ◆ Compatible with wafers up to 300 mm in size for handling and alignment.
  - ◆ Fully integrated with FOX-XP Systems.

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